

Automotive-grade N-channel 60 V, 2.3 mΩ typ., 180 A STripFET™ F6 Power MOSFET in a TO-220 package

Datasheet - production data

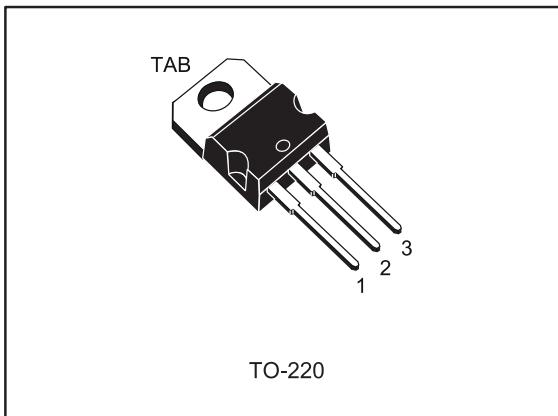
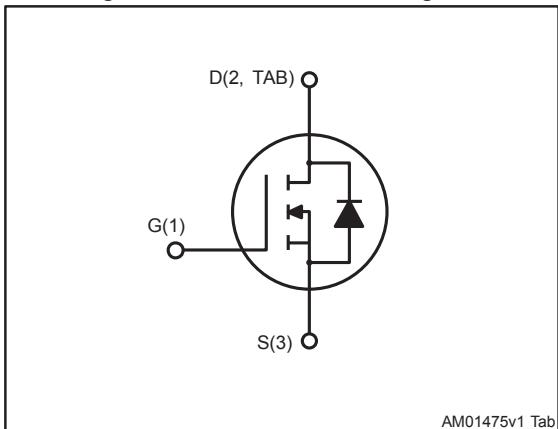


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max	I _D
STP265N6F6AG	60 V	2.85 mΩ	180 A

- AEC-Q101 qualified
- Very low on-resistance
- Very low gate charge
- High avalanche ruggedness
- Low gate drive power loss



Applications

- Switching applications

Description

This device is an N-channel Power MOSFET developed using the STripFET™ F6 technology with a new trench gate structure. The resulting Power MOSFET exhibits very low R_{DS(on)} in all packages.

Table 1: Device summary

Order code	Marking	Package	Packing
STP265N6F6AG	265N6F6	TO-220	Tube

Contents

1	Electrical ratings	3
2	Electrical characteristics	4
2.1	Electrical characteristics (curves).....	6
3	Test circuits	8
4	Package information	9
4.1	TO-220 mechanical data	10
5	Revision history	12

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	60	V
V_{GS}	Gate-source voltage	± 20	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	180	A
$I_D^{(1)}$	Drain current (continuous) at $T_C = 100^\circ\text{C}$	180	A
$I_{DM}^{(2)}$	Drain current (pulsed)	720	A
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	300	W
E_{AS}	Single pulse avalanche energy (Starting $T_J = 25^\circ\text{C}$, $I_D = 80\text{ A}$)	720	mJ
T_{stg}	Storage temperature range	$-55 \text{ to } 175$	$^\circ\text{C}$
T_J	Operating junction temperature range		

Notes:

(1) Current limited by package.

(2) Pulse width limited by safe operating area.

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max	0.5	$^\circ\text{C/W}$
$R_{thj-amb}$	Thermal resistance junction-amb max	62.5	$^\circ\text{C/W}$

2 Electrical characteristics

($T_{CASE} = 25^\circ\text{C}$ unless otherwise specified)

Table 4: On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 250 \mu\text{A}$, $V_{GS} = 0 \text{ V}$	60			V
I_{DSS}	Zero gate voltage drain current	$V_{DS} = 60 \text{ V}$, $V_{GS} = 0 \text{ V}$			1	μA
		$V_{DS} = 60 \text{ V}$, $T_C = 125^\circ\text{C}$ ⁽¹⁾ $V_{GS} = 0 \text{ V}$			100	μA
I_{GSS}	Gate-body leakage current	$V_{GS} = \pm 20 \text{ V}$, $V_{DS} = 0 \text{ V}$			± 100	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$	2		4	V
$R_{DS(\text{on})}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}$, $I_D = 60 \text{ A}$		2.3	2.85	$\text{m}\Omega$

Notes:

⁽¹⁾Defined by design, not subject to production test.

Table 5: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$, $V_{GS} = 0 \text{ V}$	-	11800	-	pF
C_{oss}	Output capacitance		-	1235	-	pF
C_{rss}	Reverse transfer capacitance		-	488	-	pF
Q_g	Total gate charge	$V_{DD} = 30 \text{ V}$, $I_D = 120 \text{ A}$, $V_{GS} = 10 \text{ V}$ (see Figure 14: "Test circuit for gate charge behavior")	-	183	-	nC
Q_{gs}	Gate-source charge		-	53	-	nC
Q_{gd}	Gate-drain charge		-	41	-	nC

Table 6: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 30 \text{ V}$, $I_D = 60 \text{ A}$, $R_G = 4.7 \Omega$, $V_{GS} = 10 \text{ V}$ (see Figure 13: "Test circuit for resistive load switching times" and Figure 18: "Switching time waveform")	-	31	-	ns
t_r	Rise time		-	165	-	ns
$t_{d(off)}$	Turn-off-delay time		-	144	-	ns
t_f	Fall time		-	63	-	ns

Table 7: Source drain diode

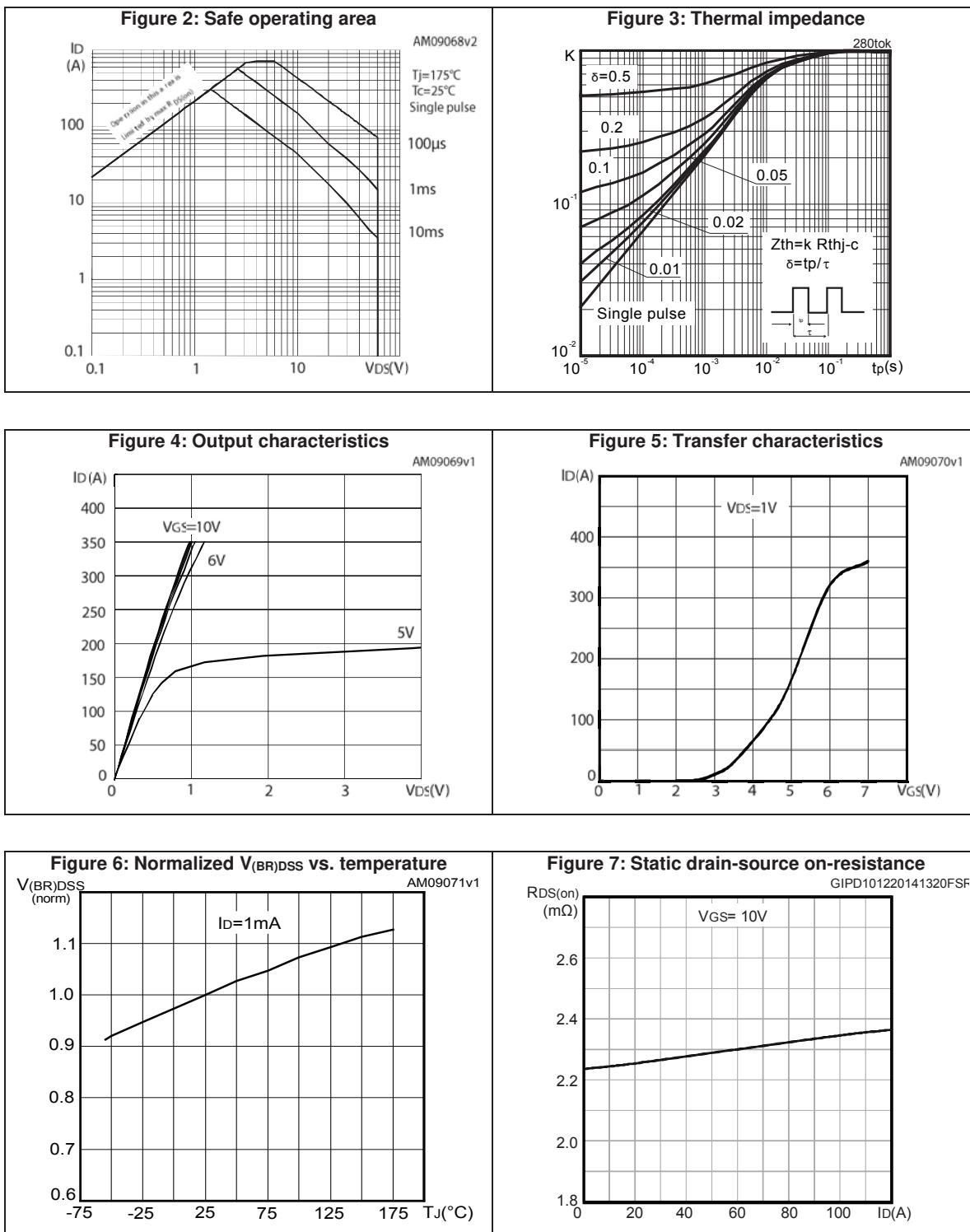
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current				180	A
I_{SDM} ⁽¹⁾	Source-drain current (pulsed)				720	A
V_{SD} ⁽²⁾	Forward on voltage	$I_{SD} = 180 \text{ A}$, $V_{GS} = 0 \text{ V}$			1.1	V
t_{rr}	Reverse recovery time	$I_{SD} = 120 \text{ A}$,	-	56	-	ns
Q_{rr}	Reverse recovery charge	$V_{DD} = 48 \text{ V}$ $di/dt = 100 \text{ A}/\mu\text{s}$, $T_j = 150 \text{ }^\circ\text{C}$	-	116	-	nC
I_{RRM}	Reverse recovery current	(see <i>Figure 15: "Test circuit for inductive load switching and diode recovery times"</i>)	-	3.8	-	A

Notes:

(1) Pulse width limited by safe operating area.

(2) Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)



STP265N6F6AG

Electrical characteristics

Figure 8: Gate charge vs. gate-source voltage

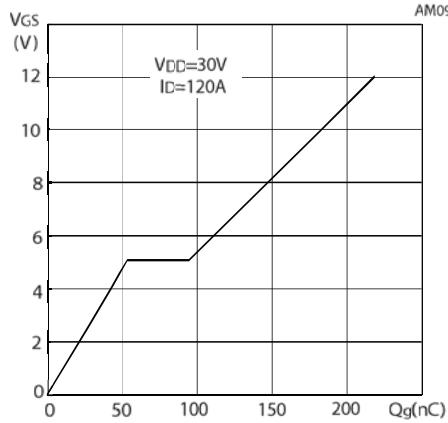


Figure 9: Capacitance variations

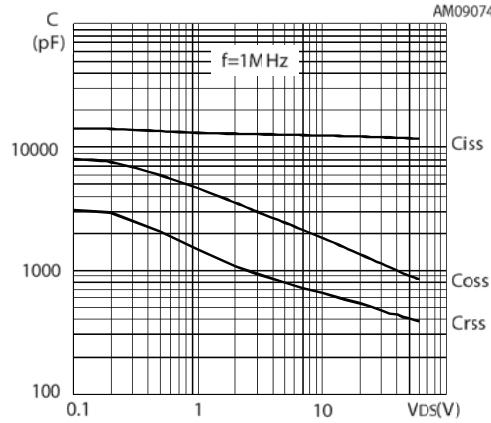


Figure 10: Normalized gate threshold voltage vs. temperature

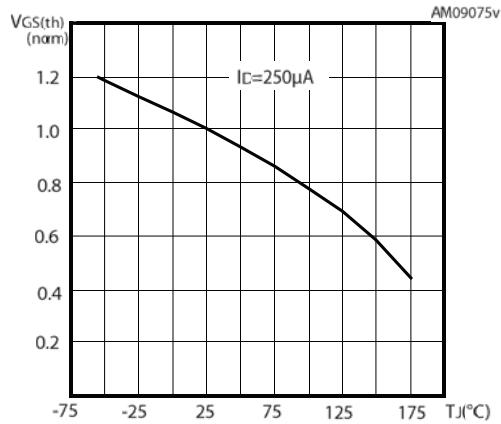


Figure 11: Normalized on resistance vs. temperature

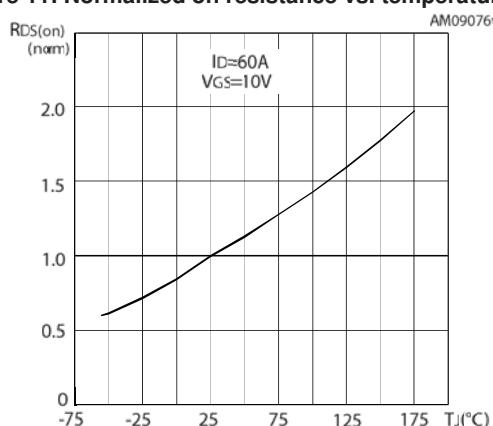
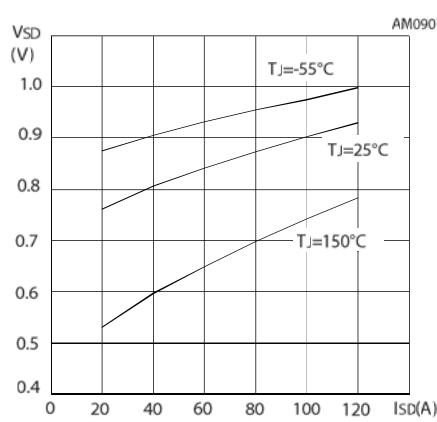
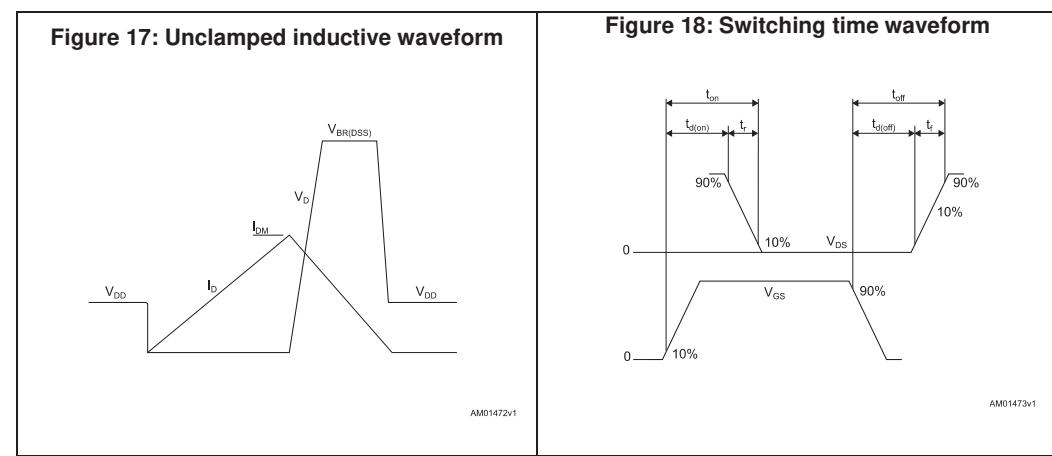
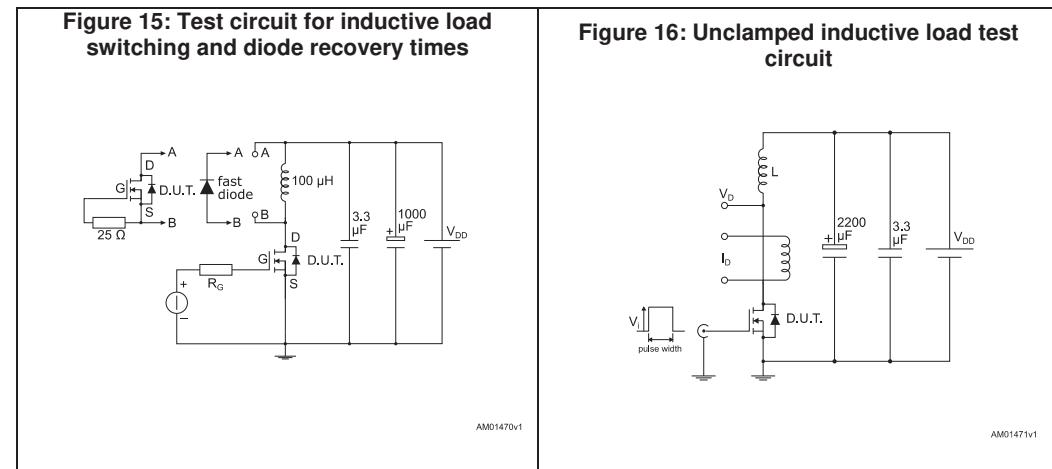
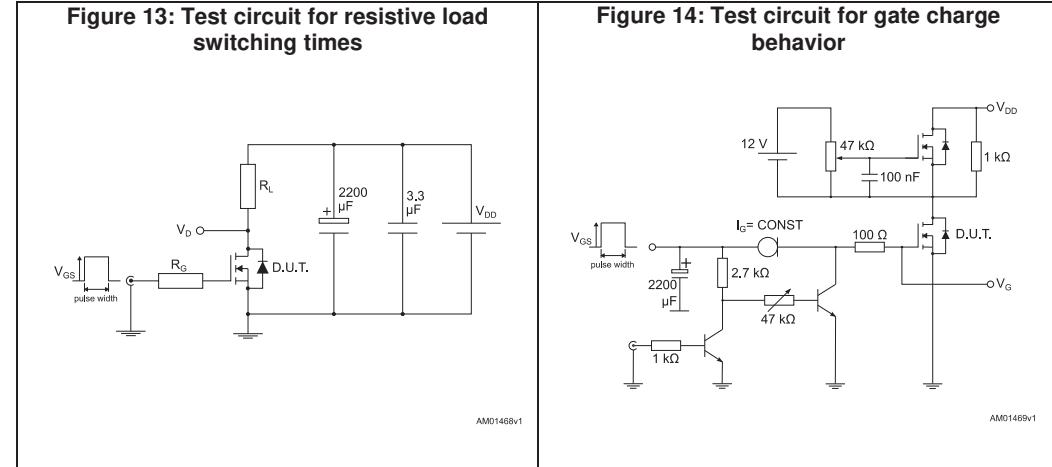


Figure 12: Source-drain diode forward characteristics



3 Test circuits



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.
ECOPACK® is an ST trademark.

4.1 TO-220 mechanical data

Figure 19: TO-220 type A package outline

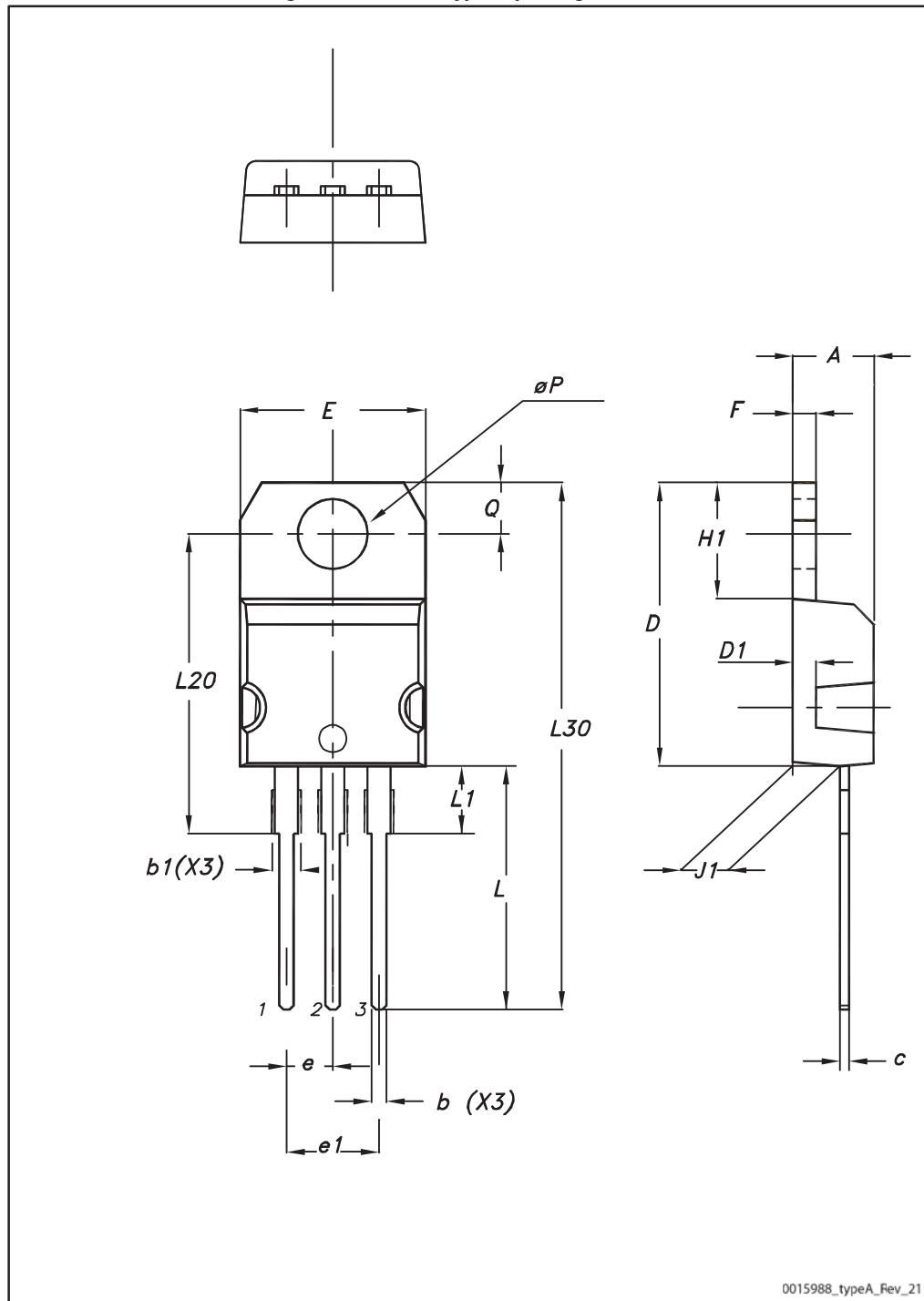


Table 8: TO-220 type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95

5 Revision history

Table 9: Document revision history

Date	Revision	Changes
10-Dec-2014	1	First release.
16-Dec-2014	2	Document status promoted from preliminary to production data.
16-Nov-2016	3	The part number STW265N6F6AG has been moved to a separate datasheet. Updated title, cover image, features and description in cover page. Updated Table 1: "Device summary" , Table 3: "Thermal data" , Section 4: "Package information" . Minor text changes.

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